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### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1937-i-ml">https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1937-i-ml</a>

# PIC16(L)F1934/6/7

**TABLE 2: 40/44-PIN SUMMARY(PIC16(L)F1934/7)**

IO	40-Pin PDIP	40-Pin UQFN	44-Pin TQFP	44-Pin QFN	ANSEL	A/D	Cap Sense	Comparator	SR Latch	Timers	CCP	EUSART	MSSP	LCD	Interrupt	Pull-up	Basic
RA0	2	17	19	19	Y	AN0	—	C12IN0-/C2OUT <sup>(1)</sup>	SRNQ <sup>(1)</sup>	—	—	—	SS <sup>(1)</sup>	SEG12	—	—	VCAP
RA1	3	18	20	20	Y	AN1	—	C12IN1-	—	—	—	—	—	SEG7	—	—	—
RA2	4	19	21	21	Y	AN2/ VREF-	—	C2IN+/ DACOUT	—	—	—	—	—	COM2	—	—	—
RA3	5	20	22	22	Y	AN3/ VREF+	—	C1IN+	—	—	—	—	—	SEG15	—	—	—
RA4	6	21	23	23	Y	—	CPS6	C1OUT	SRQ	T0CKI	—	—	—	SEG4	—	—	—
RA5	7	22	24	24	Y	AN4	CPS7	C2OUT <sup>(1)</sup>	SRNQ <sup>(1)</sup>	—	—	—	SS <sup>(1)</sup>	SEG5	—	—	VCAP
RA6	14	29	31	33	—	—	—	—	—	—	—	—	—	SEG1	—	—	OSC2/ CLKOUT VCAP
RA7	13	28	30	32	—	—	—	—	—	—	—	—	—	SEG2	—	—	OSC1/ CLKIN
RB0	33	8	8	9	Y	AN12	CPS0	—	SRI	—	—	—	—	SEG0	INT/ IOC	Y	—
RB1	34	9	9	10	Y	AN10	CPS1	C12IN3-	—	—	—	—	—	VLCD1	IOC	Y	—
RB2	35	10	10	11	Y	AN8	CPS2	—	—	—	—	—	—	VLCD2	IOC	Y	—
RB3	36	11	11	12	Y	AN9	CPS3	C12IN2-	—	—	CCP2 <sup>(1)</sup> / P2A <sup>(1)</sup>	—	—	VLCD3	IOC	Y	—
RB4	37	12	14	14	Y	AN11	CPS4	—	—	—	—	—	—	COM0	IOC	Y	—
RB5	38	13	15	15	Y	AN13	CPS5	—	—	T1G <sup>(1)</sup>	CCP3 <sup>(1)</sup> / P3A <sup>(1)</sup>	—	—	COM1	IOC	Y	—
RB6	39	14	16	16	—	—	—	—	—	—	—	—	—	SEG14	IOC	Y	ICSPCLK/ ICDCLK
RB7	40	15	17	17	—	—	—	—	—	—	—	—	—	SEG13	IOC	Y	ICSPDAT/ ICDDAT
RC0	15	30	32	34	—	—	—	—	—	T1OSO/ T1CKI	P2B <sup>(1)</sup>	—	—	—	—	—	—
RC1	16	31	35	35	—	—	—	—	—	T1OSI	CCP2 <sup>(1)</sup> / P2A <sup>(1)</sup>	—	—	—	—	—	—
RC2	17	32	36	36	—	—	—	—	—	—	CCP1/ P1A	—	—	SEG3	—	—	—
RC3	18	33	37	37	—	—	—	—	—	—	—	—	SCK/SCL	SEG6	—	—	—
RC4	23	38	42	42	—	—	—	—	—	T1G <sup>(1)</sup>	—	—	SDI/SDA	SEG11	—	—	—
RC5	24	39	43	43	—	—	—	—	—	—	—	—	SDO	SEG10	—	—	—
RC6	25	40	44	44	—	—	—	—	—	—	—	TX/CK	—	SEG9	—	—	—
RC7	26	1	1	1	—	—	—	—	—	—	—	RX/DT	—	SEG8	—	—	—
RD0	19	34	38	38	Y	—	CPS8	—	—	—	—	—	—	COM3	—	—	—
RD1	20	35	39	39	Y	—	CPS9	—	—	—	CCP4	—	—	—	—	—	—
RD2	21	36	40	40	Y	—	CPS10	—	—	—	P2B <sup>(1)</sup>	—	—	—	—	—	—
RD3	22	37	41	41	Y	—	CPS11	—	—	—	P2C	—	—	SEG16	—	—	—
RD4	27	2	2	2	Y	—	CPS12	—	—	—	P2D	—	—	SEG17	—	—	—
RD5	28	3	3	3	Y	—	CPS13	—	—	—	P1B	—	—	SEG18	—	—	—
RD6	29	4	4	4	Y	—	CPS14	—	—	—	P1C	—	—	SEG19	—	—	—
RD7	30	5	5	5	Y	—	CPS15	—	—	—	P1D	—	—	SEG20	—	—	—
RE0	8	23	25	25	Y	AN5	—	—	—	—	CCP3 <sup>(1)</sup> / P3A <sup>(1)</sup>	—	—	SEG21	—	—	—
RE1	9	24	26	26	Y	AN6	—	—	—	—	P3B	—	—	SEG22	—	—	—
RE2	10	25	27	27	Y	AN7	—	—	—	—	CCP5	—	—	SEG23	—	—	—
RE3	1	16	18	18	—	—	—	—	—	—	—	—	—	—	Y	—	MCLR/VPP
VDD	11, 32	7, 26	7, 28	7,8, 28	—	—	—	—	—	—	—	—	—	—	—	—	VDD
VSS	12, 31	6, 27	6, 29	6,30, 31	—	—	—	—	—	—	—	—	—	—	—	—	VSS

**Note 1:** Pin functions can be moved using the APFCON register.

**TABLE 3-9: PIC16(L)F1936 MEMORY MAP, BANK 15**

Bank 15	
791h	LCDCON
792h	LCDPS
793h	LCDREF
794h	LCDCST
795h	LCDRL
796h	—
797h	—
798h	LCDSE0
799h	LCDSE1
79Ah	—
79Bh	—
79Ch	—
79Dh	—
79Eh	—
79Fh	—
7A0h	LCDDATA0
7A1h	LCDDATA1
7A2h	—
7A3h	LCDDATA3
7A4h	LCDDATA4
7A5h	—
7A6h	LCDDATA6
7A7h	LCDDATA7
7A8h	—
7A9h	LCDDATA9
7AAh	LCDDATA10
7ABh	—
7ACh	—
7ADh	—
7AEh	—
7AFh	—
7B0h	—
7B1h	—
7B2h	—
7B3h	—
7B4h	—
7B5h	—
7B6h	—
7B7h	—
7B8h	Unimplemented Read as '0'
7EFh	

**Legend:**  = Unimplemented data memory locations, read as '0'.

**TABLE 3-10: PIC16(L)F1934/7 MEMORY MAP, BANK 15**

Bank 15	
791h	LCDCON
792h	LCDPS
793h	LCDREF
794h	LCDCST
795h	LCDRL
796h	—
797h	—
798h	LCDSE0
799h	LCDSE1
79Ah	LCDSE2
79Bh	—
79Ch	—
79Dh	—
79Eh	—
79Fh	—
7A0h	LCDDATA0
7A1h	LCDDATA1
7A2h	LCDDATA2
7A3h	LCDDATA3
7A4h	LCDDATA4
7A5h	LCDDATA5
7A6h	LCDDATA6
7A7h	LCDDATA7
7A8h	LCDDATA8
7A9h	LCDDATA9
7AAh	LCDDATA10
7ABh	LCDDATA11
7ACh	—
7ADh	—
7AEh	—
7AFh	—
7B0h	—
7B1h	—
7B2h	—
7B3h	—
7B4h	—
7B5h	—
7B6h	—
7B7h	—
7B8h	Unimplemented Read as '0'
7EFh	

**Legend:**  = Unimplemented data memory locations, read as '0'.

# PIC16(L)F1934/6/7

TABLE 3-11: PIC16(L)F1934/6/7 MEMORY MAP, BANK 31

Bank 31	
F8Ch	Unimplemented Read as '0'
FE3h	
FE4h	STATUS_SHAD
FE5h	WREG_SHAD
FE6h	BSR_SHAD
FE7h	PCLATH_SHAD
FE8h	FSR0L_SHAD
FE9h	FSR0H_SHAD
FEAh	FSR1L_SHAD
FEBh	FSR1H_SHAD
FECh	—
FEDh	STKPTR
FEEh	TOSL
FEFh	TOSH

**Legend:**  = Unimplemented data memory locations, read as '0'.

3.2.6 SPECIAL FUNCTION REGISTERS SUMMARY

The Special Function Register Summary for the device family are as follows:

Device	Bank(s)	Page No.
PIC16(L)F1934/6/7	0	39
	1	40
	2	41
	3	42
	4	43
	5	44
	6	45
	7	46
	8	47
	9-14	48
	15	49
	16-30	51
	31	52

## 5.2.2.6 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4X PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Word 1 must be set to use the INTOSC source as the device system clock (FOSC<2:0> = 100).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<2:0> in Configuration Word 1 (SCS<1:0> = 00).
- The IRCF bits in the OSCCON register must be set to the 8 MHz HFINTOSC set to use (IRCF<3:0> = 1110).
- The SPLLEN bit in the OSCCON register must be set to enable the 4xPLL, or the PLEN bit of the Configuration Word 2 must be programmed to a '1'.

**Note:** When using the PLEN bit of the Configuration Word 2, the 4xPLL cannot be disabled by software and the 8 MHz HFINTOSC option will no longer be available.

The 4xPLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to '1x'. The SCS bits must be set to '00' to use the 4xPLL with the internal oscillator.

## 5.2.2.7 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC, MFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-7). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC, MFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-7 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-1.

Start-up delay specifications are located in the oscillator tables in the applicable Electrical Specifications Chapter.

## 5.4 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device. This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC internal oscillator block as the clock source and go back to Sleep without waiting for the external oscillator to become stable.

Two-Speed Start-up provides benefits when the oscillator module is configured for LP, XT or HS modes. The Oscillator Start-up Timer (OST) is enabled for these modes and must count 1024 oscillations before the oscillator can be used as the system clock source.

If the oscillator module is configured for any mode other than LP, XT or HS mode, then Two-Speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

If the OST count reaches 1024 before the device enters Sleep mode, the OSTS bit of the OSCSTAT register is set and program execution switches to the external oscillator. However, the system may never operate from the external oscillator if the time spent awake is very short.

**Note:** Executing a `SLEEP` instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCSTAT register to remain clear.

### 5.4.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Word 1) = 1; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = 00.
- FOSC<2:0> bits in the Configuration Word 1 configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

**TABLE 5-1: OSCILLATOR SWITCHING DELAYS**

Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	LFINTOSC <sup>(1)</sup> MFINTOSC <sup>(1)</sup> HFINTOSC <sup>(1)</sup>	31 kHz 31.25 kHz-500 kHz 31.25 kHz-16 MHz	Oscillator Warm-up Delay (TWARM)
Sleep/POR	EC, RC <sup>(1)</sup>	DC – 32 MHz	2 cycles
LFINTOSC	EC, RC <sup>(1)</sup>	DC – 32 MHz	1 cycle of each
Sleep/POR	Timer1 Oscillator LP, XT, HS <sup>(1)</sup>	32 kHz-20 MHz	1024 Clock Cycles (OST)
Any clock source	MFINTOSC <sup>(1)</sup> HFINTOSC <sup>(1)</sup>	31.25 kHz-500 kHz 31.25 kHz-16 MHz	2 $\mu$ s (approx.)
Any clock source	LFINTOSC <sup>(1)</sup>	31 kHz	1 cycle of each
Any clock source	Timer1 Oscillator	32 kHz	1024 Clock Cycles (OST)
PLL inactive	PLL active	16-32 MHz	2 ms (approx.)

**Note 1:** PLL inactive.

# PIC16(L)F1934/6/7

## EXAMPLE 11-4: ERASING ONE ROW OF PROGRAM MEMORY -

```
; This row erase routine assumes the following:
; 1. A valid address within the erase block is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)

        BCF      INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL  EEADRL
        MOVF     ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF    EEADRL
        MOVF     ADDRH,W        ; Load upper 6 bits of erase address boundary
        MOVWF    EEADRH
        BSF      EECON1,EEPGD    ; Point to program memory
        BCF      EECON1,CFGSR    ; Not configuration space
        BSF      EECON1,FREE     ; Specify an erase operation
        BSF      EECON1,WREN     ; Enable writes

        MOV LW   55h            ; Start of required sequence to initiate erase
        MOVWF    EECON2         ; Write 55h
        MOV LW   0AAh          ;
        MOVWF    EECON2         ; Write AAh
        BSF      EECON1,WR      ; Set WR bit to begin erase
        NOP                      ; Any instructions here are ignored as processor
                                ; halts to begin erase sequence
        NOP                      ; Processor will stop here and wait for erase complete.

                                ; after erase processor continues with 3rd instruction

        BCF      EECON1,WREN     ; Disable writes
        BSF      INTCON,GIE     ; Enable interrupts
```

Required  
Sequence

# PIC16(L)F1934/6/7

**TABLE 12-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB**

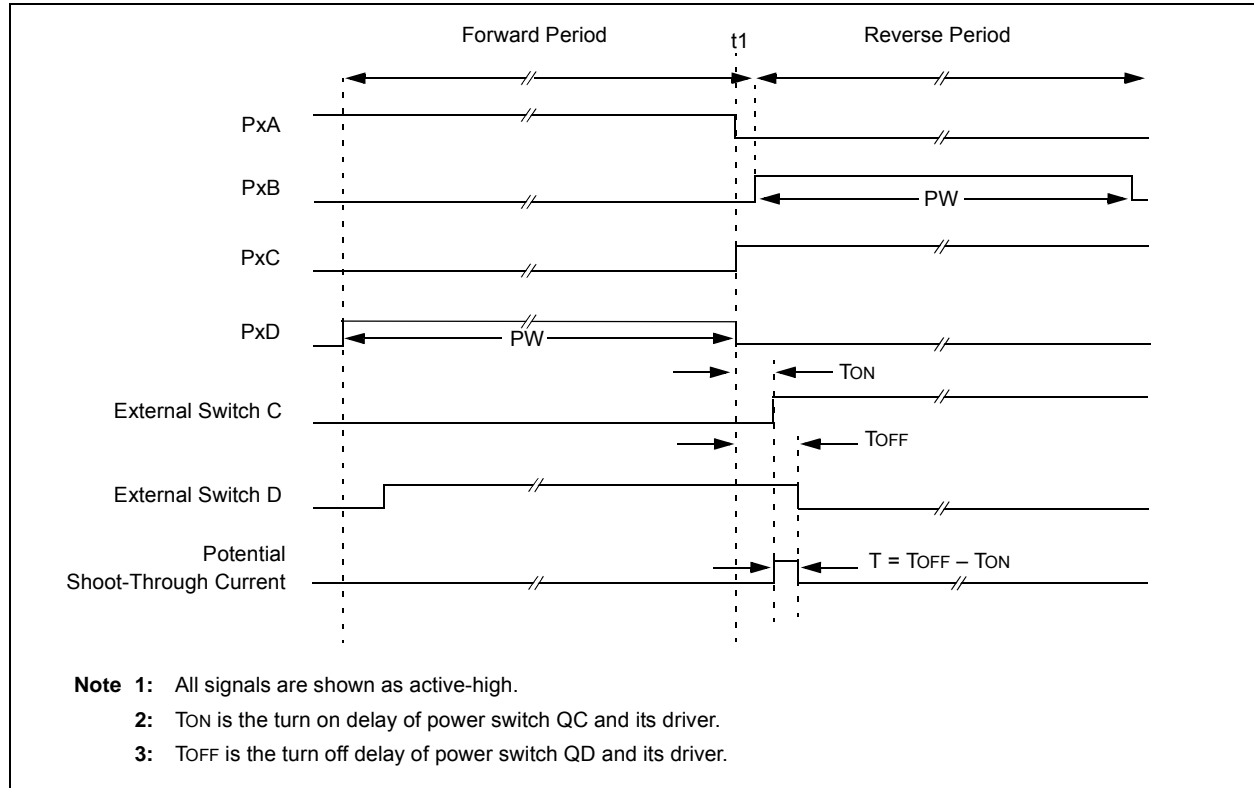
Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS<4:0>					GO/DONE	ADON	163
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	139
APFCON	—	CCP3SEL	T1GSEL	P2BSEL	SRNQSEL	C2OUTSEL	SSSEL	CCP2SEL	131
CCPxCON	PxM<1:0>		DCxB<1:0>		CCPxM<3:0>				234
CPSCON0	CPSON	—	—	—	CPSRNG<1:0>		CPSOUT	TOXCS	323
CPSCON1	—	—	—	—	CPSCH<3:>				324
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	98
IOCBP	IOCBP7	IOCBP6	IOCBP5	IOCBP4	IOCBP3	IOCBP2	IOCBP1	IOCBP0	152
IOCBN	IOCBN7	IOCBN6	IOCBN5	IOCBN4	IOCBN3	IOCBN2	IOCBN1	IOCBN0	152
IOCBF	IOCBF7	IOCBF6	IOCBF5	IOCBF4	IOCBF3	IOCBF2	IOCBF1	IOCBF0	152
LATB	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	138
LCDCON	LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>		329
LCDSE0	SE7	SE6	SE5	SE4	SE3	SE2	SE1	SE0	333
LCDSE1	SE15	SE14	SE13	SE12	SE11	SE10	SE9	SE8	333
OPTION_REG	WPUEN	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			193
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	138
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GSS<1:0>		204
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	138
WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	139

**Legend:** x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by PORTB.



NOTES:

**FIGURE 23-13: EXAMPLE OF PWM DIRECTION CHANGE AT NEAR 100% DUTY CYCLE**

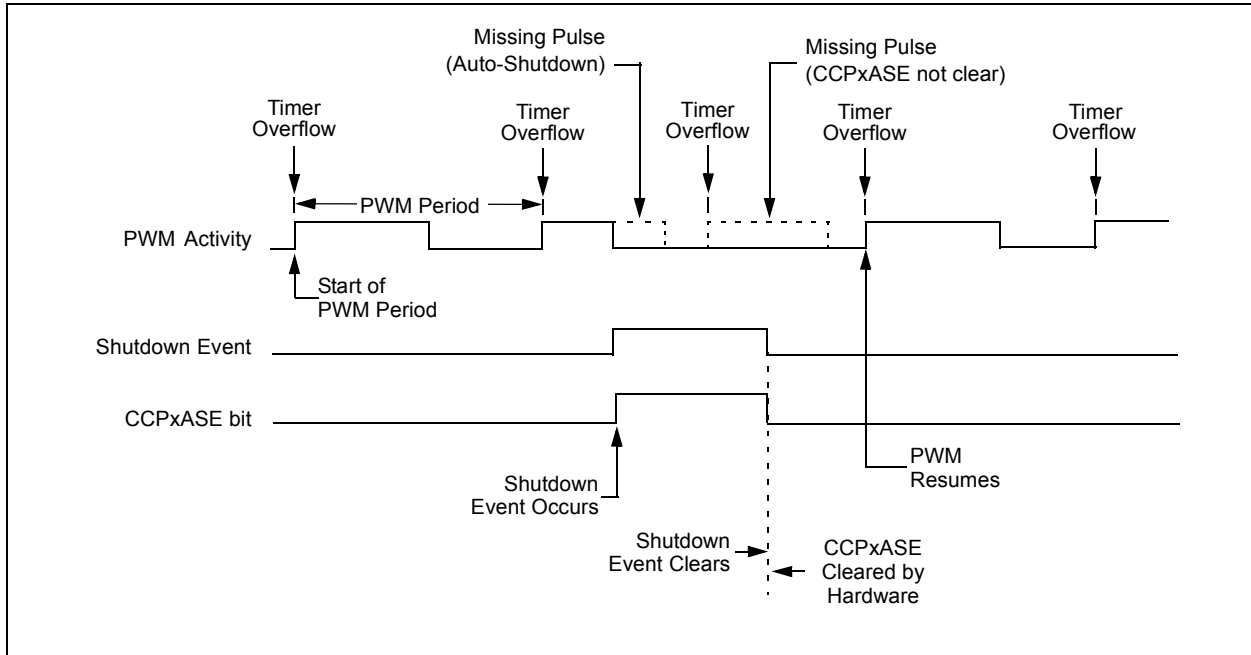


## 23.4.4 AUTO-RESTART MODE

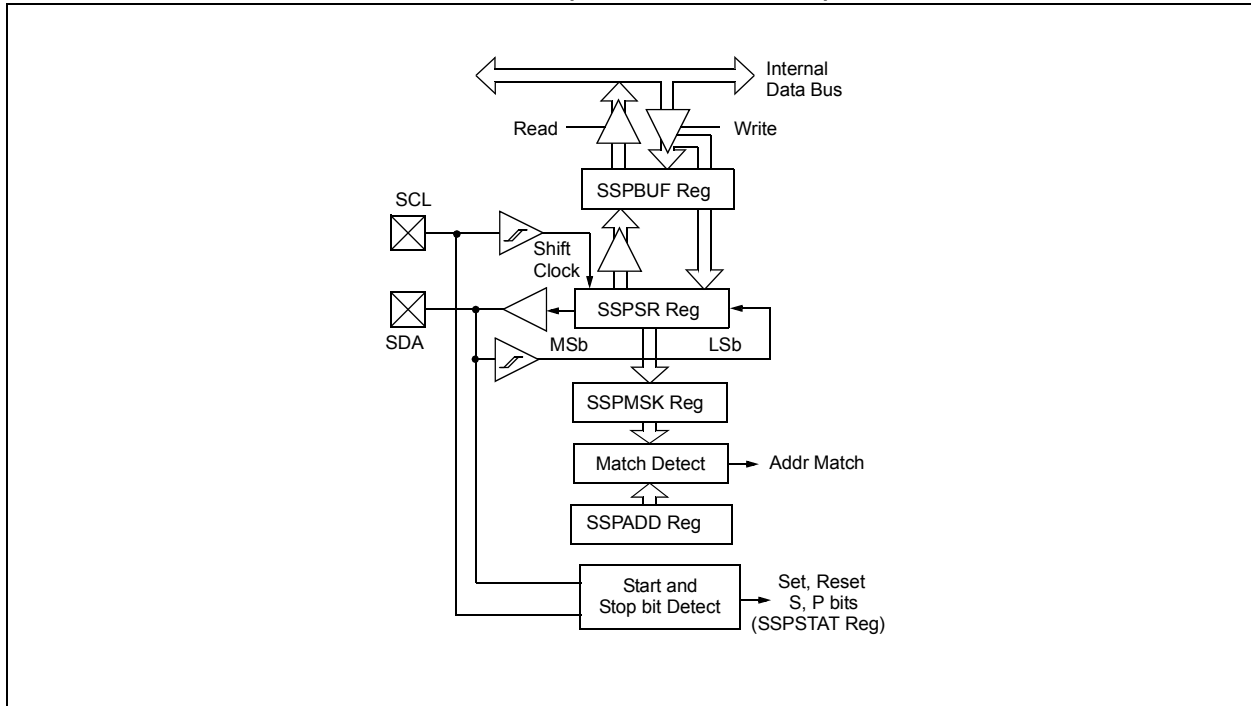
The Enhanced PWM can be configured to automatically restart the PWM signal once the auto-shutdown condition has been removed. Auto-restart is enabled by setting the PxRSEN bit in the PWMxCON register.

If auto-restart is enabled, the CCPxASE bit will remain set as long as the auto-shutdown condition is active. When the auto-shutdown condition is removed, the CCPxASE bit will be cleared via hardware and normal operation will resume.

**FIGURE 23-15: PWM AUTO-SHUTDOWN WITH AUTO-RESTART (PxRSEN = 1)**



**FIGURE 24-3: MSSP BLOCK DIAGRAM (I<sup>2</sup>C™ SLAVE MODE)**



## 24.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a Chip Select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCK)
- Serial Data Out (SDO)
- Serial Data In (SDI)
- Slave Select ( $\overline{SS}$ )

Figure 24-1 shows the block diagram of the MSSP module when operating in SPI Mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 24-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. With either the master or the slave device, data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 24-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDO output pin which is connected to, and received by, the slave's SDI input pin. The slave device transmits information out on its SDO output pin, which is connected to, and received by, the master's SDI input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSB position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on

its SDO pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDO pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After 8 bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

## 25.1.2.8 Asynchronous Reception Set-up:

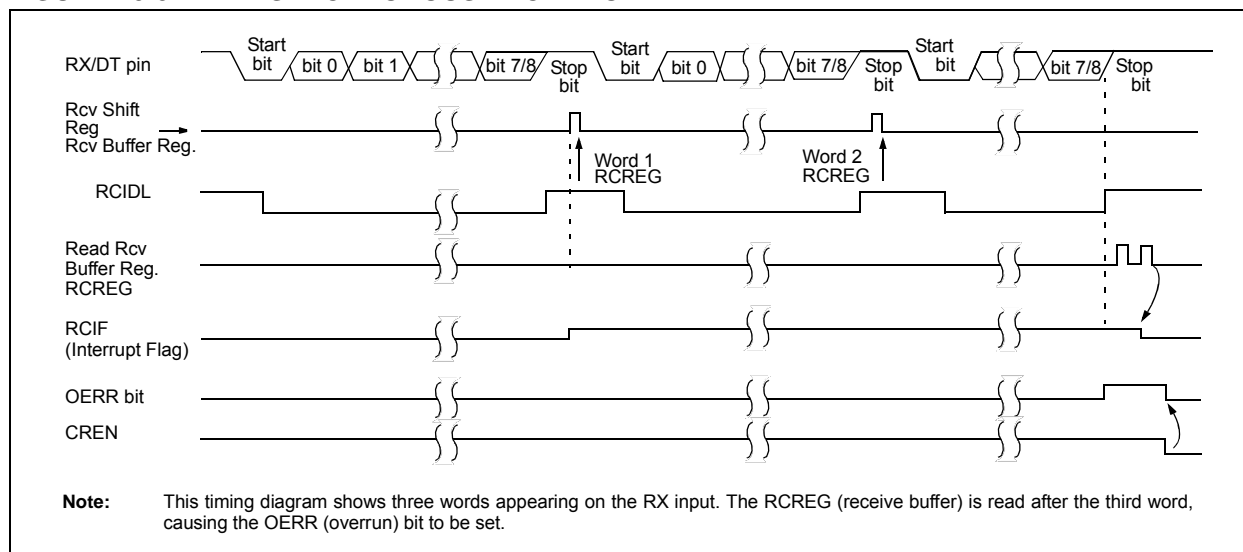
1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 25.3 “EUSART Baud Rate Generator (BRG)”**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RCSTA register to get the error flags and, if 9-bit data reception is enabled, the ninth data bit.
9. Get the received 8 Least Significant data bits from the receive buffer by reading the RCREG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

## 25.1.2.9 9-bit Address Detection Mode Set-up

This mode would typically be used in RS-485 systems. To set up an Asynchronous Reception with Address Detect Enable:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 25.3 “EUSART Baud Rate Generator (BRG)”**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the ninth bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RCSTA register to get the error flags. The ninth data bit will always be set.
10. Get the received 8 Least Significant data bits from the receive buffer by reading the RCREG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

**FIGURE 25-5: ASYNCHRONOUS RECEPTION**



## 26.5 Timer Resources

To measure the change in frequency of the capacitive sensing oscillator, a fixed time base is required. For the period of the fixed time base, the capacitive sensing oscillator is used to clock either Timer0 or Timer1. The frequency of the capacitive sensing oscillator is equal to the number of counts in the timer divided by the period of the fixed time base.

## 26.6 Fixed Time Base

To measure the frequency of the capacitive sensing oscillator, a fixed time base is required. Any timer resource or software loop can be used to establish the fixed time base. It is up to the end user to determine the method in which the fixed time base is generated.

**Note:** The fixed time base can not be generated by the timer resource that the capacitive sensing oscillator is clocking.

### 26.6.1 TIMER0

To select Timer0 as the timer resource for the CPS module:

- Set the T0XCS bit of the CPSCON0 register.
- Clear the TMR0CS bit of the OPTION\_REG register.

When Timer0 is chosen as the timer resource, the capacitive sensing oscillator will be the clock source for Timer0. Refer to **Section 20.0 “Timer0 Module”** for additional information.

### 26.6.2 TIMER1

To select Timer1 as the timer resource for the CPS module, set the TMR1CS<1:0> of the T1CON register to ‘11’. When Timer1 is chosen as the timer resource, the capacitive sensing oscillator will be the clock source for Timer1. Because the Timer1 module has a gate control, developing a time base for the frequency measurement can be simplified by using the Timer0 overflow flag.

It is recommend that the Timer0 overflow flag, in conjunction with the Toggle mode of the Timer1 gate, be used to develop the fixed time base required by the software portion of the CPS module. Refer to **Section 21.12 “Timer1 Gate Control Register”** for additional information.

**TABLE 26-2: TIMER1 ENABLE FUNCTION**

TMR1ON	TMR1GE	Timer1 Operation
0	0	Off
0	1	Off
1	0	On
1	1	Count Enabled by input

## 26.7 Software Control

The software portion of the CPS module is required to determine the change in frequency of the capacitive sensing oscillator. This is accomplished by the following:

- Setting a fixed time base to acquire counts on Timer0 or Timer1.
- Establishing the nominal frequency for the capacitive sensing oscillator.
- Establishing the reduced frequency for the capacitive sensing oscillator due to an additional capacitive load.
- Set the frequency threshold.

### 26.7.1 NOMINAL FREQUENCY (NO CAPACITIVE LOAD)

To determine the nominal frequency of the capacitive sensing oscillator:

- Remove any extra capacitive load on the selected CPSx pin.
- At the start of the fixed time base, clear the timer resource.
- At the end of the fixed time base save the value in the timer resource.

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator for the given time base. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed time base.

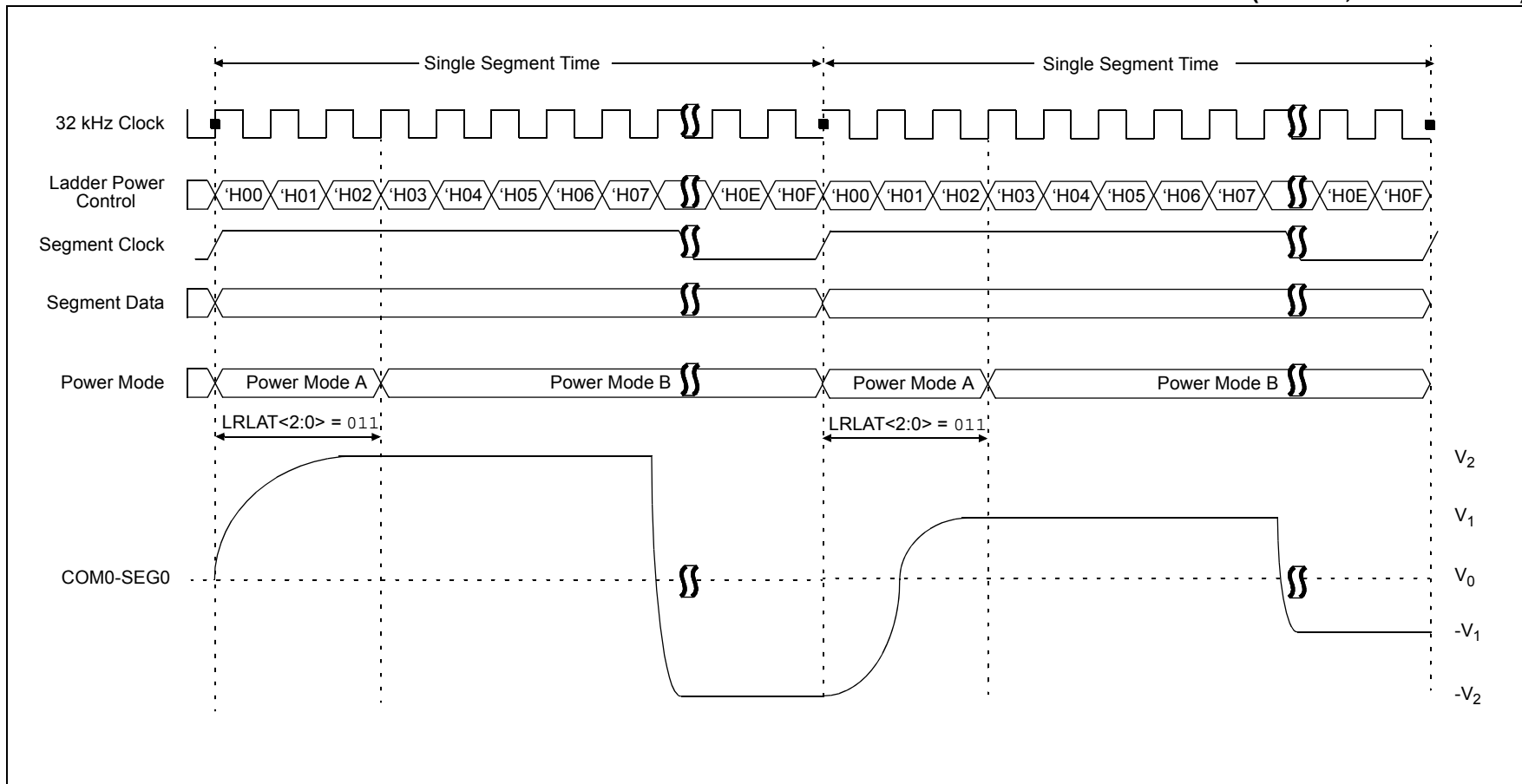
### 26.7.2 REDUCED FREQUENCY (ADDITIONAL CAPACITIVE LOAD)

The extra capacitive load will cause the frequency of the capacitive sensing oscillator to decrease. To determine the reduced frequency of the capacitive sensing oscillator:

- Add a typical capacitive load on the selected CPSx pin.
- Use the same fixed time base as the nominal frequency measurement.
- At the start of the fixed time base, clear the timer resource.
- At the end of the fixed time base save the value in the timer resource.

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator with an additional capacitive load. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed time base. This frequency should be less than the value obtained during the nominal frequency measurement.

FIGURE 27-5: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE A WAVEFORM (1/2 MUX, 1/2 BIAS DRIVE)





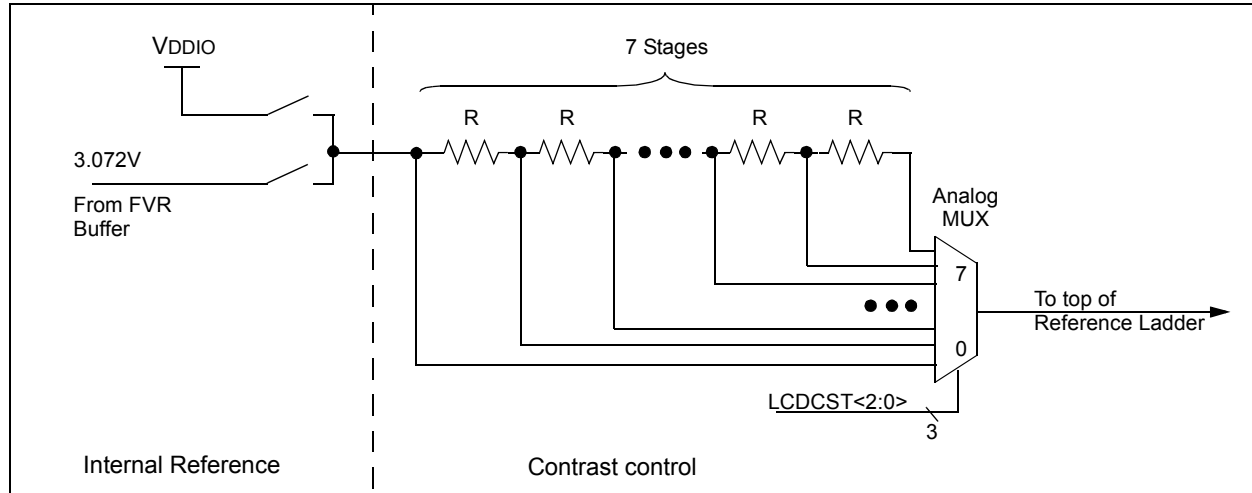
## 27.4.4 CONTRAST CONTROL

The LCD contrast control circuit consists of a seven-tap resistor ladder, controlled by the LCDCST bits. Refer to Figure 27-7.

The contrast control circuit is used to decrease the output voltage of the signal source by a total of approximately 10%, when  $LCDCST = 111$ .

Whenever the LCD module is inactive ( $LCDA = 0$ ), the contrast control ladder will be turned off (open).

**FIGURE 27-7: INTERNAL REFERENCE AND CONTRAST CONTROL BLOCK DIAGRAM**



## 27.4.5 INTERNAL REFERENCE

Under firmware control, an internal reference for the LCD bias voltages can be enabled. When enabled, the source of this voltage can be either  $V_{DDIO}$  or a voltage 3 times the main fixed voltage reference (3.072V). When no internal reference is selected, the LCD contrast control circuit is disabled and LCD bias must be provided externally.

Whenever the LCD module is inactive ( $LCDA = 0$ ), the internal reference will be turned off.

When the internal reference is enabled and the Fixed Voltage Reference is selected, the LCDIRI bit can be used to minimize power consumption by tying into the LCD Reference Ladder Automatic Power mode switching. When  $LCDIRI = 1$  and the LCD reference ladder is in Power mode 'B', the LCD internal FVR buffer is disabled.

**Note:** The LCD module automatically turns on the Fixed Voltage Reference when needed.

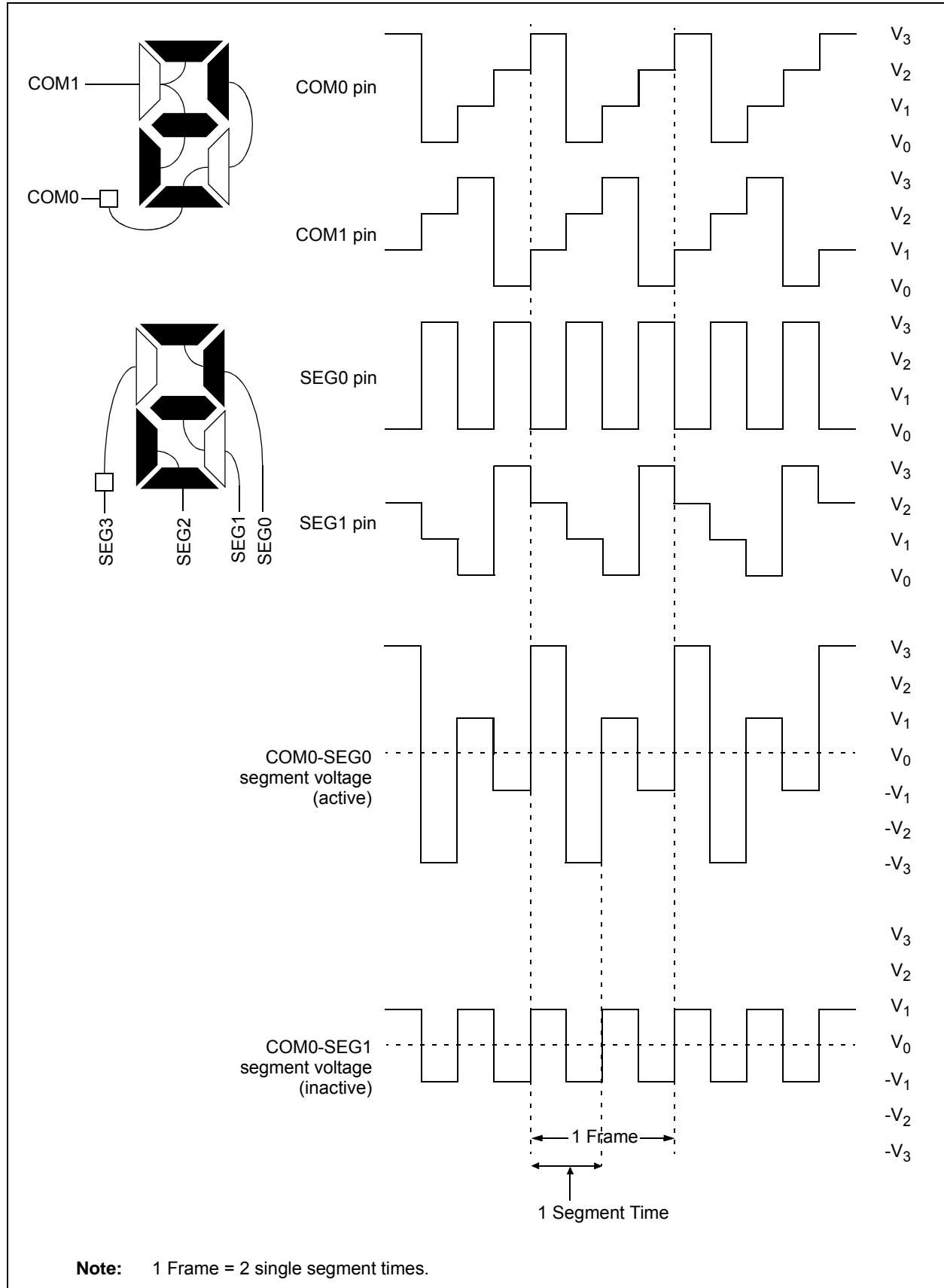
## 27.4.6 VLCD<3:1> PINS

The  $VLCD<3:1>$  pins provide the ability for an external LCD bias network to be used instead of the internal ladder. Use of the  $VLCD<3:1>$  pins does not prevent use of the internal ladder. Each VLCD pin has an independent control in the LCDREF register (Register 27-3), allowing access to any or all of the LCD Bias signals. This architecture allows for maximum flexibility in different applications.

For example, the  $VLCD<3:1>$  pins may be used to add capacitors to the internal reference ladder, increasing the drive capacity.

For applications where the internal contrast control is insufficient, the firmware can choose to only enable the VLCD3 pin, allowing an external contrast control circuit to use the internal reference divider.

**FIGURE 27-11: TYPE-A WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE**



## 28.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- MCLR/VPP
- VDD
- VSS

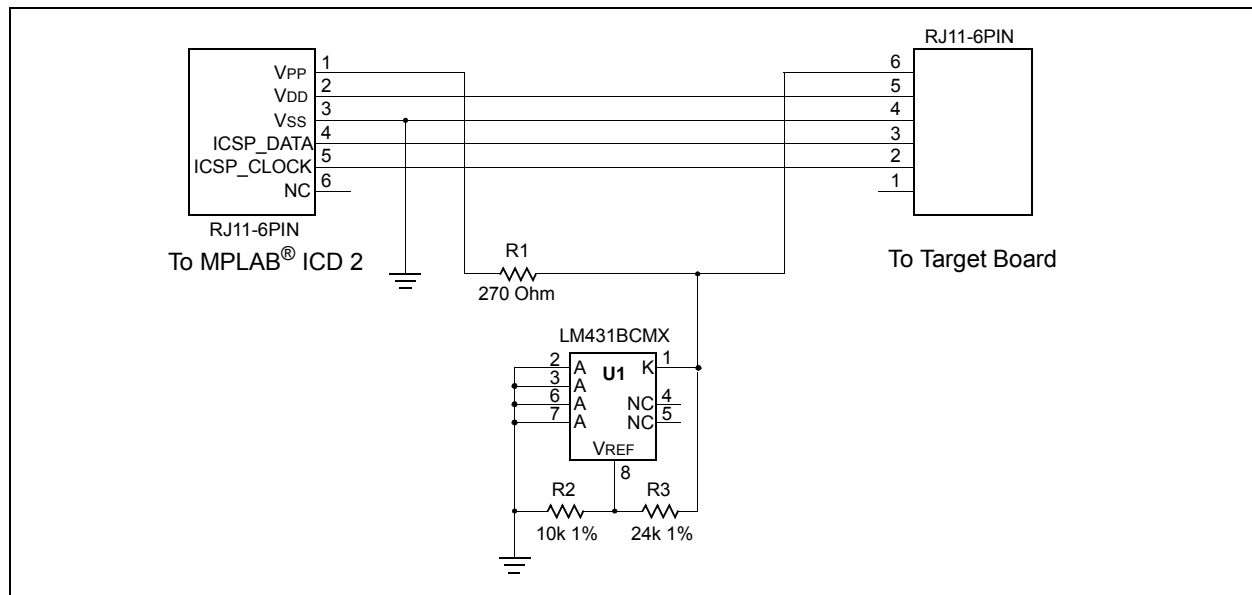
In Program/Verify mode the Program Memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the “PIC16193X/PIC16LF193X Memory Programming Specification” (DS41360).

### 28.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on MCLR/VPP to  $V_{IH}$ .

Some programmers produce  $V_{PP}$  greater than  $V_{IH}$  (9.0V), an external circuit is required to limit the  $V_{PP}$  voltage. See Figure 28-1 for example circuit.

**FIGURE 28-1: VPP LIMITER EXAMPLE CIRCUIT**



**Note:** The MPLAB® ICD 2 produces a  $V_{PP}$  voltage greater than the maximum  $V_{PP}$  specification of the PIC16(L)F1934/6/7.

## 30.4 DC Characteristics: PIC16(L)F1934/6/7-I/E

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D032 D032A D033 D034 D034A	VIL	<b>Input Low Voltage</b>					
		I/O PORT:					
		with TTL buffer	—	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
			—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
		with Schmitt Trigger buffer	—	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
		with I <sup>2</sup> C™ levels	—	—	0.3 VDD	V	
		with SMBus levels	—	—	0.8	V	2.7V ≤ VDD ≤ 5.5V
D040 D040A D041 D042 D043A D043B	VIH	MCLR, OSC1 (RC mode) <sup>(1)</sup>	—	—	0.2 VDD	V	
		OSC1 (HS mode)	—	—	0.3 VDD	V	
		<b>Input High Voltage</b>					
		I/O ports:					
		with TTL buffer	2.0	—	—	V	4.5V ≤ VDD ≤ 5.5V
			0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 4.5V
		with Schmitt Trigger buffer	0.8 VDD	—	—	V	2.0V ≤ VDD ≤ 5.5V
D060 D061	IIL	with I <sup>2</sup> C™ levels	0.7 VDD	—	—	V	
		with SMBus levels	2.1	—	—	V	2.7V ≤ VDD ≤ 5.5V
		MCLR	0.8 VDD	—	—	V	
		OSC1 (HS mode)	0.7 VDD	—	—	V	
		OSC1 (RC mode)	0.9 VDD	—	—	V	VDD > 2.0V (Note 1)
		<b>Input Leakage Current<sup>(2)</sup></b>					
		I/O ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance @ 85°C
D070*	IPUR			± 5	± 1000	nA	125°C
		MCLR <sup>(3)</sup>	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD @ 85°C
D070*	IPUR	<b>Weak Pull-up Current</b>					
			25 25	100 140	200 300	μA	VDD = 3.3V, VPIN = VSS VDD = 5.0V, VPIN = VSS
D080	VOL	<b>Output Low Voltage<sup>(4)</sup></b>					
		I/O ports	—	—	0.6	V	IOL = 8mA, VDD = 5V IOL = 6mA, VDD = 3.3V IOL = 1.8mA, VDD = 1.8V
D090	VOH	<b>Output High Voltage<sup>(4)</sup></b>					
		I/O ports	VDD - 0.7	—	—	V	IOH = 3.5mA, VDD = 5V IOH = 3mA, VDD = 3.3V IOH = 1mA, VDD = 1.8V
D101* D101A*	COSC2 CIO	<b>Capacitive Loading Specs on Output Pins</b>					
		OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
		All I/O pins	—	—	50	pF	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

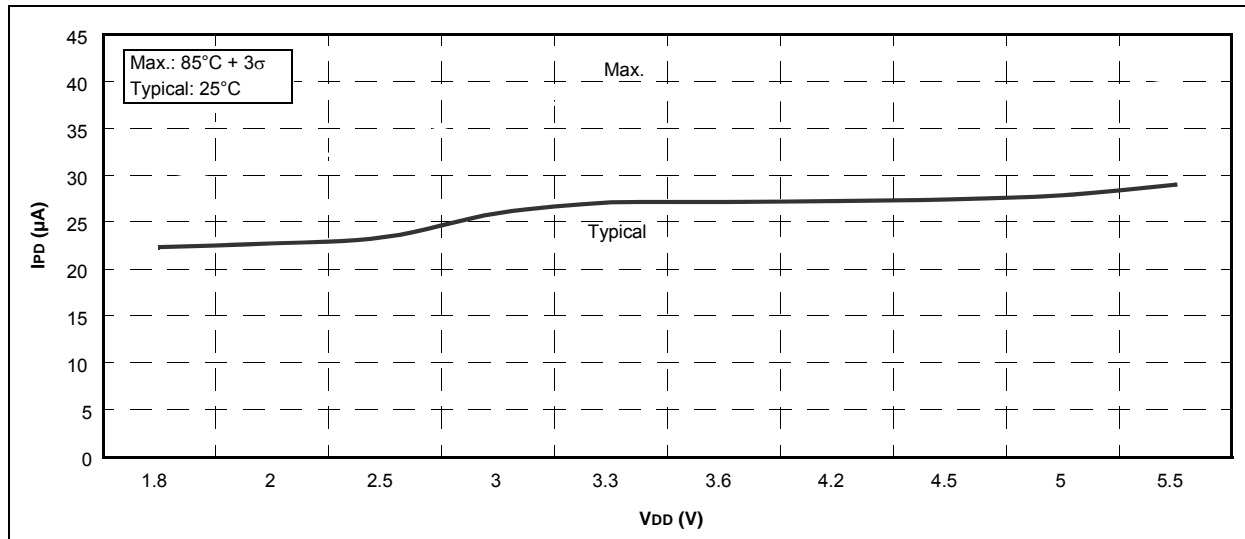
**Note 1:** In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

**2:** Negative current is defined as current sourced by the pin.

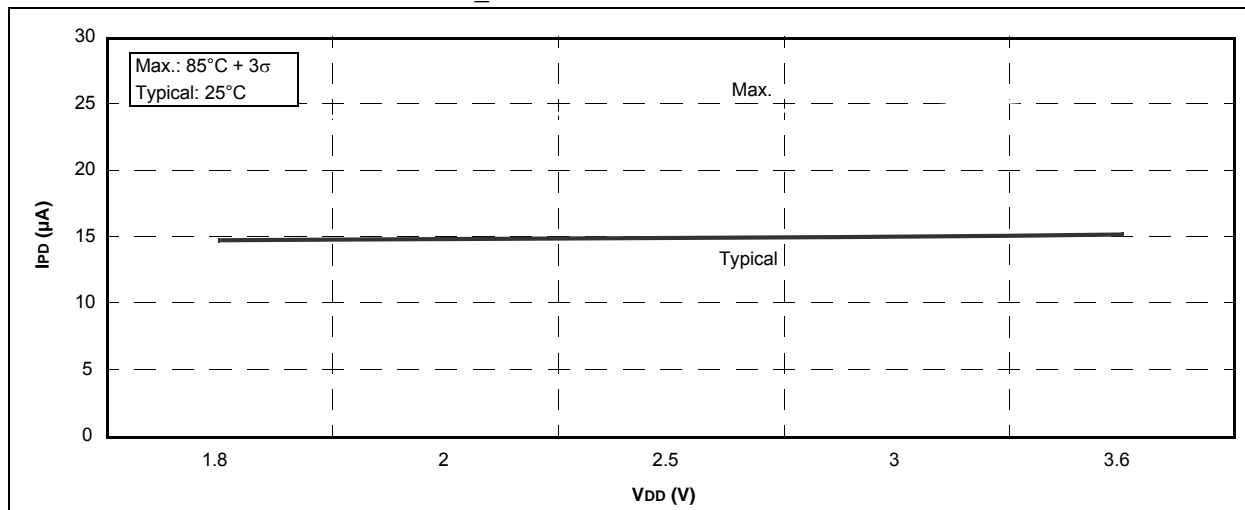
**3:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

**4:** Including OSC2 in CLKOUT mode.

**FIGURE 31-69: PIC16F1937 WDT**



**FIGURE 31-70: PIC16LF1937 FVR\_DAC**



**FIGURE 31-71: PIC16F1937 FVR\_DAC**

